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- Qualification in Accordance With AEC-Q100[†]
- Qualified for Automotive Applications
- Customer-Specific Configuration Control Can Be Supported Along With Major-Change Approval
- Bidirectional Transceiver
- Meet or Exceed the Requirements of ANSI Standard RS-485 and ISO 8482:1987(E)
- High-Speed Low-Power LinBiCMOS™ Circuitry
- Designed for High-Speed Operation in Both Serial and Parallel Applications
- Low Skew
- Designed for Multipoint Transmission on Long Bus Lines in Noisy Environments
- Very Low Disabled Supply-Current Requirements . . . 200 μA Maximum
- Wide Positive and Negative Input/Output Bus Voltage Ranges
- Driver Output Capacity . . . ±60 mA
- Thermal-Shutdown Protection
- Driver Positive-and Negative-Current Limiting
- Open-Circuit Fail-Safe Receiver Design
- Receiver Input Sensitivity . . . ±200 mV Max

[†] Contact factory for details. Q100 qualification data available on request.

description/ordering information

The SN65LBC176 differential bus transceiver is a monolithic, integrated circuit designed for bidirectional data communication on multipoint bus-transmission lines. It is designed for balanced transmission lines and meets ANSI Standard RS-485 and ISO 8482:1987(E).

ORDERING INFORMATION

TA	PACKAGE [‡]		PACKAGE [‡]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 125°C	SOIC – D	Tape and reel	SN65LBC176QDRQ1	L176Q1		

[‡]Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.



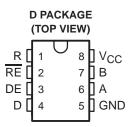
Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



- Operate From a Single 5-V Supply
- Glitch-Free Power-Up and Power-Down Protection



Function Tables

	DRIVER			
INPUT	ENABLE	OUTPUTS		
D	DE	Α	В	
Н	Н	Н	L	
L	Н	L	Н	
Х	L	Z	Z	

RECEIVER

DIFFERENTIAL INPUTS A-B	ENABLE RE	OUTPUT R
$V_{ID} \ge 0.2 V$	L	Н
$-0.2 \text{ V} < \text{V}_{\text{ID}} < 0.2 \text{ V}$	L	?
$V_{ID} \leq -0.2 V$	L	L
Х	Н	Z
Open	L	Н

H = high level, L = low level, ? = indeterminate,

X = irrelevant, Z = high impedance (off)

1

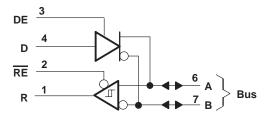
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description (continued)

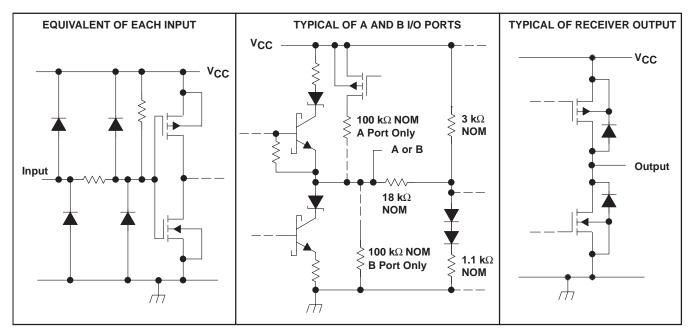
The SN65LBC176 combines a 3-state, differential line driver and a differential input line receiver, both of which operate from a single 5-V power supply. The driver and receiver have active-high and active-low enables, respectively, which can externally connect together to function as a direction control. The driver differential outputs and the receiver differential inputs connect internally to form a differential input/output (I/O) bus port that is designed to offer minimum loading to the bus whenever the driver is disabled or $V_{CC} = 0$. This port features wide positive and negative common-mode voltage ranges, making the device suitable for party-line applications. Very low device supply current can be achieved by disabling the driver and the receiver. Both the driver and receiver are available as cells in the Texas Instruments LinASICTM Library.

This transceiver is suitable for ANSI Standard RS-485 and ISO 8482:1987 (E) applications to the extent that they are specified in the operating conditions and characteristics section of this data sheet. Certain limits contained in the ANSI Standard RS-485 and ISO 8482:1987 (E) are not met or cannot be tested over the entire extended temperature range.

logic diagram (positive logic)



schematics of inputs and outputs





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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V _{CC} (see Note 1)	
Voltage range at any bus terminal	\ldots -10 V to 15 V
Input voltage, V _I (D, DE, R, or RE)	$\dots \dots \dots -0.3$ V to V _{CC} + 0.5 V
Continuous total power dissipation	See Dissipation Rating Table
Operating free-air temperature range, T _A SN65LBC176Q	–40°C to 125°C
Storage temperature range, T _{stg}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	

⁺ Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values, except differential I/O bus voltage, are with respect to network ground terminal.

DISSIPATION RATING TABLE							
PACKAGE	$T_A \le 25^{\circ}C$ POWER RATING	DERATING FACTOR ABOVE T _A = 25°C	T _A = 70°C POWER RATING	T _A = 85°C POWER RATING	T _A = 125°C POWER RATING		
D	725 mW	5.8 mW/°C	464 mW	377 mW	145 mW		

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V _{CC}		4.75	5	5.25	V
				12	
voltage at any bus terminal (separately or common r	oltage at any bus terminal (separately or common mode), VI or VIC			-7	V
High-level input voltage, VIH	D, DE, and RE	2			V
Low-level input voltage, VIL	D, DE, and RE			0.8	V
Differential input voltage, VID (see Note 2)				±12	V
I Park Jacob and and an analytic	Driver			-60	mA
High-level output current, IOH	Receiver			-400	μA
Level and a structure of the	Driver			60	
Low-level output current, IOL	Receiver			8	mA
Operating free-air temperature, TA	SN65LBC176Q	-40		125	°C

NOTE 2: Differential input/output bus voltage is measured at the noninverting terminal A with respect to the inverting terminal B.



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DRIVER SECTION

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TE	TEST CONDITIONS			MAX	UNIT
VIK	Input clamp voltage	lı = – 18 mA				-1.5	V
VO	Output voltage	IO = 0			0	6	V
VOD1	Differential output voltage	IO = 0			1.5	6	V
V _{OD3}	Differential output voltage	$V_{test} = -7 V$ to 12 V,	See Figure 2,	See Note 3	1.1		V
V _{OD2}	Differential output voltage	R _L = 54 Ω,	See Figure 1,	See Note 3	1.1		V
Δ V _{OD}	Change in magnitude of differential output voltage					±0.2	V
		1				3	
Voc	Common-mode output voltage	$R_L = 54 \Omega$ or 100 Ω,	See Figure 1	See Figure 1		-1	V
A VOC	Change in magnitude of common-mode output voltage [†]				±0.2	V	
		Output disabled,	V _O = 12 V			1	
IO	Output current	See Note 4	$V_{O} = -7 V$			-0.8	mA
IIН	High-level input current	VI = 2.4 V	-			-100	μA
۱ _{IL}	Low-level input current	VI = 0.4 V				-100	μA
		$V_{O} = -7 V$				-250	
		$V_{O} = 0$	$V_{O} = 0$			-150	
IOS	Short-circuit output current	VO = VCC			050	mA	
		V _O = 12 V]	250	
ICC	Supply current	V _I = 0 or V _{CC} , No load	Receiver disabled and driver enabled			1.75	mA
		100 1080	Receiver and driver disabled			0.25	

[†]Δ | V_{OD} | and Δ | V_{OC} | are the changes in magnitude of V_{OD} and V_{OC}, respectively, that occur when the input changes from a high level to a low level.

NOTES: 3. This device meets the ANSI Standard RS-485 V_{OD} requirements above 0°C only.

4. This applies for both power on and off; refer to ANSI Standard RS-485 for exact conditions.

switching characteristics over recommended ranges of supply voltage and operating free-air temperature

PARAMETER		TEST C	MIN	TYP†	MAX	UNIT	
^t d(OD)	Differential output delay time			8		31	ns
tt(OD)	Differential output transition time	$R_L = 54 \Omega,$ $C_L = 50 pF,$ 12			ns		
tsk(p)	Pulse skew (t _{d(ODH)} - t _{d(ODL)})	eee rigare e				6	ns
^t PZH	Output enable time to high level	R _L = 110 Ω,	See Figure 4			65	ns
tPZL	Output enable time to low level	R _L = 110 Ω,	See Figure 5			65	ns
^t PHZ	Output disable time from high level	R _L = 110 Ω,	See Figure 4			105	ns
^t PLZ	Output disable time from low level	R _L = 110 Ω,	See Figure 5			105	ns

[†] All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^{\circ}\text{C}$.



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SYMBOL EQUIVALENTS						
DATA SHEET PARAMETER	RS-485					
Vo	V _{oa} , V _{ob}					
VOD1	Vo					
V _{OD2}	$V_t (R_L = 54 \Omega)$					
V _{OD3}	V _t (test termination measurement 2)					
Δ V _{OD}	$ V_t - \overline{V}_t $					
V _{OC}	V _{OS}					
	V _{os} – V _{os}					
IOS	None					
IO	l _{ia} , l _{ib}					

RECEIVER SECTION

electrical characteristics over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature (unless otherwise noted)

	PARAMETER		TEST CONDITIONS		MIN	TYP [†]	MAX	UNIT
VIT+	Positive-going input threshold voltage	V _O = 2.7 V,	$I_{O} = -0.4 \text{ mA}$				0.2	V
V_{IT-}	Negative-going input threshold voltage	V _O = 0.5 V,	I _O = 8 mA		-0.2‡			V
V _{hys}	Hysteresis voltage (V _{IT +} – V _{IT –}) (see Figure 4)					50		mV
VIK	Enable-input clamp voltage	I _I = -18 mA					-1.5	V
VOH	High-level output voltage	V _{ID} = 200 mV,	I _{OH} = -400 μA,	See Figure 6	2.7			V
VOL	Low-level output voltage	V _{ID} = 200 mV,	I _{OL} = 8 mA,	See Figure 6			0.45	V
I _{OZ}	High-impedance-state output current	$V_{O} = 0.4 V \text{ to } 2.4 V$	/				±20	μΑ
		Other input = 0 V,	VI = 12 V				1	
1	Line input current	See Note 5	V _I = -7 V				-0.8	mA
Iн	High-level enable-input current	V _{IH} = 2.7 V	-				-100	μA
١ _L	Low-level enable-input current	V _{IL} = 0.4 V					-100	μA
rj	Input resistance				12			kΩ
	Supply ourront	$V_{I} = 0 \text{ or } V_{CC},$	Receiver enabled a	nd driver disabled			3.9	mA
ICC	Supply current	No load	Receiver and driver	disabled			0.25	ША

 [†] All typical values are at V_{CC} = 5 V, T_A = 25°C.
 [‡] The algebraic convention, in which the less-positive (more-negative) limit is designated minimum, is used in this data sheet for common-mode input voltage and threshold voltage levels only.

NOTE 5: This applies for both power on and power off. Refer to ANSI Standard RS-485 for exact conditions.

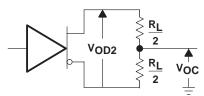


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switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L = 15 \text{ pF}$

	PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
^t PLH	Propagation delay time, low- to high-level single-ended output		11	37	ns
^t PHL	Propagation delay time, high- to low-level single-ended output	$V_{ID} = -1.5$ V to 1.5 V, See Figure 7	11	37	ns
^t sk(p)	Pulse skew (t _{d(ODH)} – t _{d(ODL)})			10	ns
^t PZH	Output enable time to high level			35	ns
t _{PZL}	Output enable time to low level	See Figure 8		35	ns
^t PHZ	Output disable time from high level	See Figure 8		35	ns
t _{PLZ}	Output disable time from low level	See rigule o		35	ns

PARAMETER MEASUREMENT INFORMATION





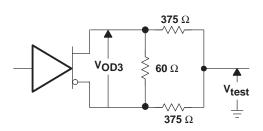
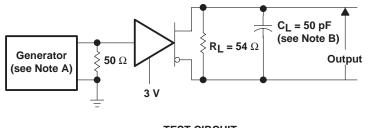


Figure 2. Driver VOD3





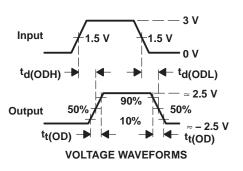
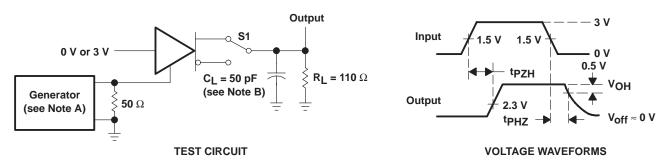


Figure 3. Driver Test Circuit and Voltage Waveforms







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PARAMETER MEASUREMENT INFORMATION

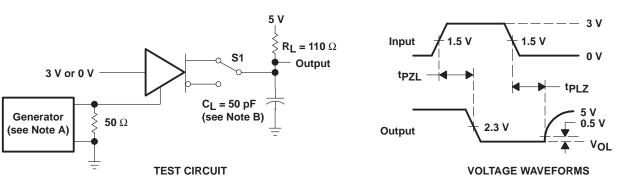


Figure 5. Driver Test Circuit and Voltage Waveforms

- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, t_f \leq 6 ns, t_f \leq 8 ns, t_f
 - B. CL includes probe and jig capacitance.

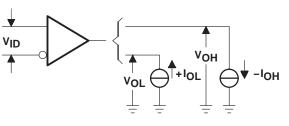
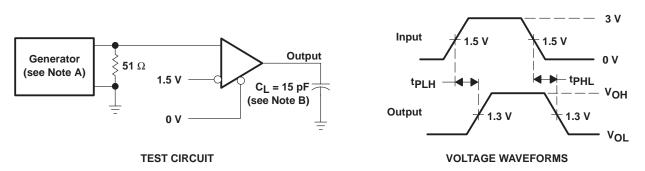


Figure 6. Receiver VOH and VOL

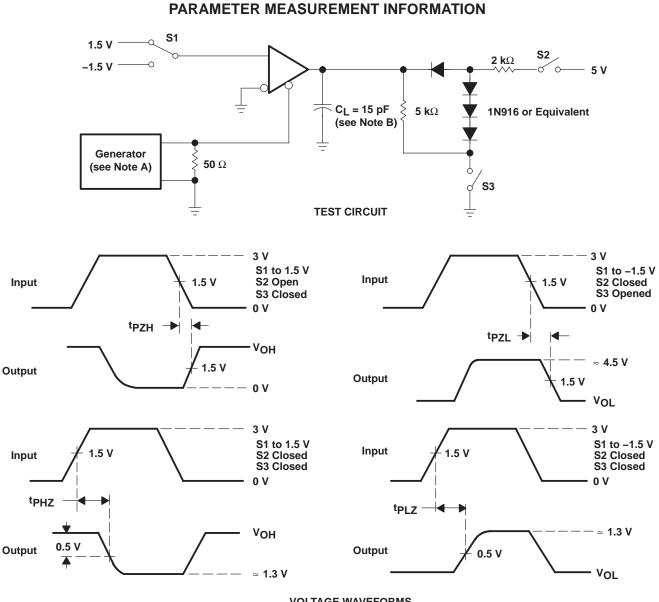


- NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, t_f \leq 6 ns, t_f \leq 6 ns, Z_O = 50 Ω .
 - B. CL includes probe and jig capacitance.

Figure 7. Receiver Test Circuit and Voltage Waveforms



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VOLTAGE WAVEFORMS



NOTES: A. The input pulse is supplied by a generator having the following characteristics: PRR \leq 1 MHz, 50% duty cycle, t_f \leq 6 ns, t_f \leq 6 ns, $Z_{O} = 50 \Omega$.

B. C_{I} includes probe and jig capacitance.

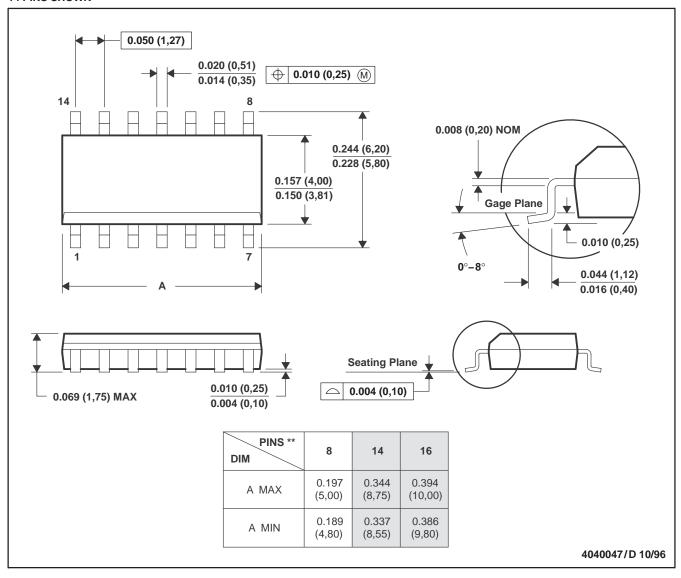


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MECHANICAL INFORMATION

PLASTIC SMALL-OUTLINE PACKAGE

D (R-PDSO-G**) 14 PINS SHOWN



NOTES: A. All linear dimensions are in inches (millimeters).

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0.006 (0,15).

D. Falls within JEDEC MS-012



PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Pin Drawing		Pins Package Eco Plan ⁽²⁾ Qty		Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN65LBC176QDRQ1	ACTIVE	SOIC	D	8	2500	Pb-Free (RoHS)	CU NIPDAU	Level-2-250C-1 YEAR/ Level-1-235C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - May not be currently available - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

None: Not yet available Lead (Pb-Free).

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⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDECindustry standard classifications, and peak solder temperature.

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D (R-PDSO-G8)

PLASTIC SMALL-OUTLINE PACKAGE



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D. Falls within JEDEC MS-012 variation AA.



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